

IN THE CLAIMS

Please cancel claim 8, and amend claims 9 and 11 as presented below:

1. (Cancelled)

2. (Cancelled)

3. (Previously Presented) A method for manufacturing a printed circuit board comprising the steps of:

- coating a lower surface and an upper surface of an insulative substrate respectively with a lower surface metal foil and an upper surface metal foil, the thickness of which is less than that of the lower surface metal foil;
- forming an opening in the upper surface metal foil at a location corresponding to a blind via hole formation portion of the insulative substrate;
- forming a blind via hole, the bottom of which is the lower surface metal foil, by emitting a laser against the blind via hole formation portion through the opening;
- applying a conductor to the blind via hole; and
- forming an upper surface pattern and a lower surface pattern by respectively etching the upper surface metal foil and the lower surface metal foil, wherein the upper surface and lower surface metal foil coating step includes a step of coating the upper surface and the lower surface, respectively, with an upper surface metal foil and a lower surface metal foil that have the same thickness, and a step for etching the upper surface metal foil.

4. (Cancelled)

5. (Previously Presented) A method for manufacturing a printed circuit board comprising the steps of:

coating a lower surface and an upper surface of an insulative substrate respectively with a lower surface metal foil and an upper surface metal foil, the thickness of which is less than that of the lower surface metal foil;

forming an opening in the upper surface metal foil at a location corresponding to a blind via hole formation portion of the insulative substrate;

forming a blind via hole, the bottom of which is the lower surface metal foil, by emitting a laser against the blind via hole formation portion through the opening;

applying a conductor to the blind via hole; and

forming an upper surface pattern and a lower surface pattern by respectively etching the upper surface metal foil and the lower surface metal foil, wherein the upper surface and lower surface metal foil coating step includes a step for coating the upper surface and the lower surface, respectively, with an upper surface metal foil and a lower surface metal foil that have the same thickness, and a step for performing a sandblast treatment to the upper surface metal foil so that the thickness of the upper surface metal foil becomes less than that of the lower surface metal foil.

6. (Previously Presented) The printed circuit board manufacturing method according to claim 3, wherein the thickness of the upper surface pattern is 2 to 12 μ m.

7. (Previously Presented) The printed circuit board manufacturing method according to claim 3, wherein the thickness of the lower surface pattern is 15 to 25 μ m.

8. (Cancelled)

9. (Currently Amended) A method for manufacturing a printed circuit board comprising the steps of:

coating a lower surface and an upper surface of an insulative substrate respectively with a lower surface metal[[,]] foil and an upper surface metal foil, the thickness of which is less than that of the lower surface metal foil;

forming an upper surface pattern and a lower surface pattern by respectively etching the upper surface metal foil and the lower surface metal foil, wherein the upper surface pattern has an opening exposing the upper surface of the insulative substrate at a location corresponding to a blind via hole formation portion, and the lower surface pattern covers the lower surface of the insulative substrate at a location corresponding to the blind via hole formation portion;

forming a blind via hole, the bottom of which is the lower surface pattern, by emitting a laser against the[[,]] insulative substrate through the opening; and

applying a conductor to the blind via hole, wherein the upper surface end lower surface metal foil coating step includes a step of coating the upper surface and the lower surface, respectively, with an upper surface metal foil and a lower surface metal foil that have the same thickness, and a step for etching the upper surface metal foil.

10. (Cancelled)

11. (Currently Amended) A method for manufacturing a printed circuit board comprising the steps of:

coating a lower surface and an upper surface of an insulative substrate respectively with a lower surface metal[[,]] foil and, an upper surface metal foil, the thickness of which is less than that of the lower surface metal foil;

forming an upper surface pattern and a lower surface pattern by respectively etching the upper surface metal foil and the lower surface metal foil, wherein the upper surface pattern has an opening exposing the upper surface of the insulative substrate at a location corresponding to a blind via hole formation portion, and the lower surface pattern covers the lower surface of the insulative substrate at a location corresponding to the blind via hole formation portion;

forming a blind via hole, the bottom of which is the lower surface pattern, by emitting a laser against the insulative substrate through the opening; and

applying a conductor to the blind via hole, wherein the upper surface and lower surface metal foil coating step includes a step for coating the upper surface and the lower surface, respectively, with an upper surface metal foil and a lower surface metal foil that have the same thickness, and a step for performing a sandblast treatment to the upper surface metal foil so that the thickness of the upper surface metal foil becomes less than that of the lower surface metal foil.

12. (Previously Presented) The printed circuit board manufacturing method according to claim 9, wherein the thickness of the upper surface pattern is 2 to 12 μ m.

13. (Previously Presented) The printed circuit board manufacturing method according to claim 9, wherein the thickness of the lower surface pattern is 15 to 25 μ m.

14. (Previously Presented) The printed Circuit board manufacturing method according to claim 5, wherein the thickness of the upper surface pattern is 2 to 12 μ m.

15. (Previously Presented) The printed Circuit board manufacturing method according to claim 5, wherein the thickness of the lower surface pattern is 15 to 25 μ m.

16. (Previously Presented) The printed circuit board manufacturing method according to claim 11, wherein the thickness of the upper surface pattern is 2 to 12 μ m.

17. (Previously Presented) The printed circuit board manufacturing method according to claim 11, wherein the thickness of the lower surface pattern is 15 to 25 μ m.